MC74ACT241

Octal Buffer/Line Driver with 3-State Outputs

The MC74ACT241 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

Features

- 3−State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- TTL Compatible Inputs
- Pb−Free Packages are Available

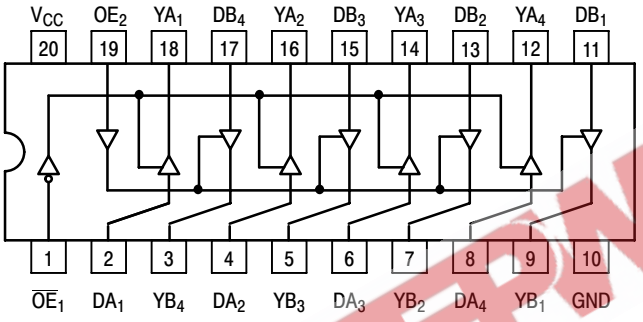

Figure 1. Pinout: 20−Lead Packages Conductors
(Top View)

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_1$	D	(Pins 12, 14, 16, 18)
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

TRUTH TABLE

Inputs		Outputs
OE_2	D	(Pins 3, 5, 7, 9)
H	L	L
H	H	H
L	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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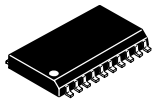
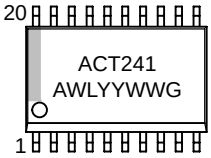
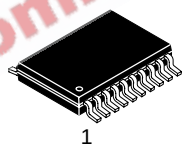
MARKING DIAGRAMS

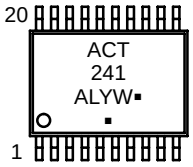


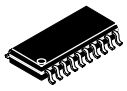
SOIC−20W
DW SUFFIX
CASE 751D



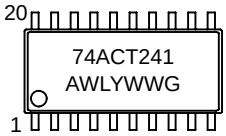


TSSOP−20
DT SUFFIX
CASE 948E





SOEIAJ−20
M SUFFIX
CASE 967



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC}+0.5$	V
V_O	DC Output Voltage (Note 1)		$-0.5 \le V_O \le V_{CC}+0.5$	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_O	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current per Output Pin		±50	mA
I_{GND}	DC Ground Current per Output Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		+150	°C
θ_{JA}	Thermal Resistance	SOIC TSSOP	96 128	°C/W
P_D	Power Dissipation in Still Air at 85°C	SOIC TSSOP	500 450	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% − 35%	UL 94 V−0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 > 1000	V
$I_{Latchup}$	Latchup Performance	Above V_{CC} and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22−A114−A.
3. Tested to EIA/JESD22−A115−A.
4. Tested to JESD22−C101−A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	DC Input Voltage (Referenced to GND)		4.5		5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0		V_{CC}	V
T_A	Operating Temperature, All Package Types		−40	25	+85	°C
t_r, t_f	Input Rise and Fall Time (Note 7)	V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0	10 8.0	10 8.0	ns/V
I_{OH}	Output Current − High		−	−	−24	mA
I_{OL}	Output Current − Low		−	−	24	mA

6. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
7. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = −40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V V	I_{OUT} = −50 μA
		4.5 5.5	−	3.86 4.86	3.76 4.76	V V	*V_{IN} = V_{IL} or V_{IH} −24 mA I_{OH} −24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V V	I_{OUT} = 50 μA
		4.5 5.5	−	0.36 0.36	0.44 0.44	V V	*V_{IN} = V_{IL} or V_{IH} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	−	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Maximum I_{CC}/Input	5.5	0.6	−	1.5	mA	V_I = V_{CC} − 2.1 V
I_{OZ}	Maximum 3−State Current	5.5	−	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5 5.5	−	−	75 −75	mA mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	−	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS t_r = t_f = 3.0 ns (For Figures and Waveforms, See Figures 2, 3, and 4.)

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C C_L = 50 pF			T_A = −40°C to +85°C C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay Data to Output	5.0	1.5	6.5	9.0	1.5	10.0	ns
t_{PHL}	Propagation Delay Data to Output	5.0	1.5	7.0	9.0	1.5	10.0	ns
t_{PZH}	Output Enable Time	5.0	1.5	6.0	9.0	1.0	10.0	ns
t_{PZL}	Output Enable Time	5.0	1.5	7.0	10.0	1.5	11.0	ns
t_{PHZ}	Output Disable Time	5.0	1.5	8.0	10.5	1.5	11.5	ns
t_{PLZ}	Output Disable Time	5.0	2.0	7.0	10.5	1.5	11.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

SWITCHING WAVEFORMS

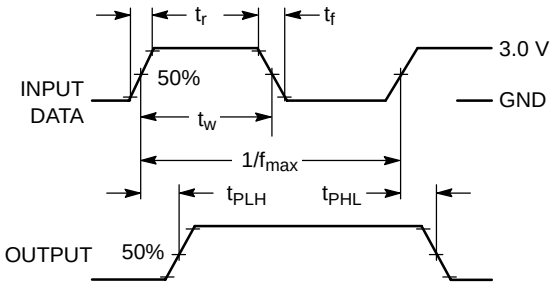


Figure 2.

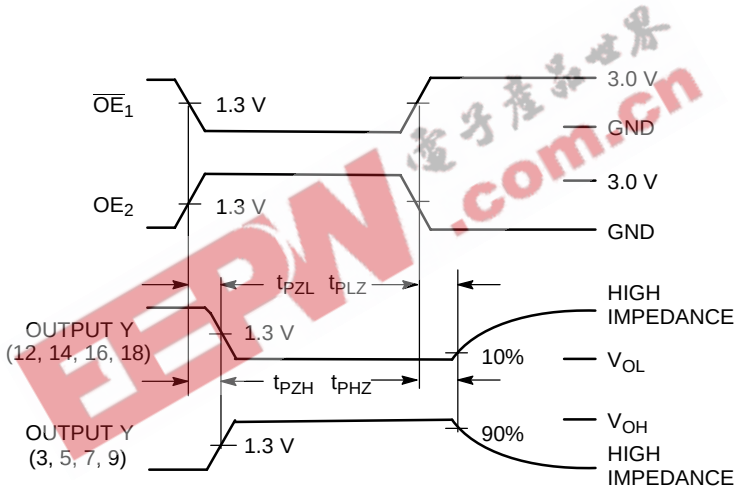
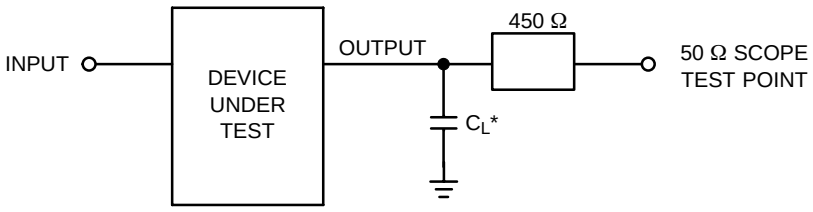


Figure 3.



*Includes all probe and jig capacitance

Figure 4. Test Circuit

ORDERING INFORMATION

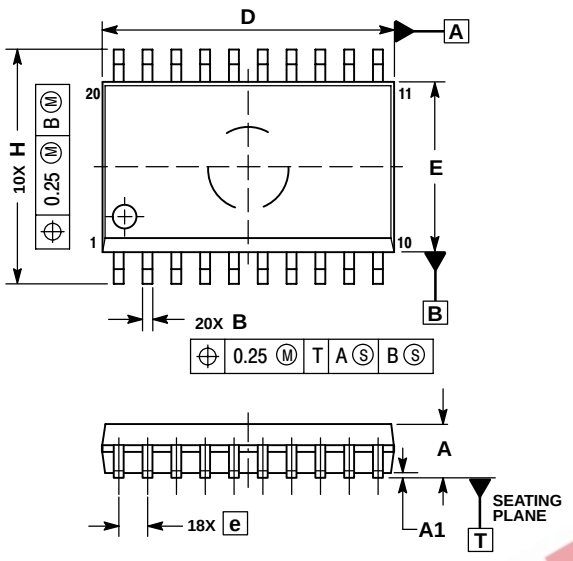
Device	Package	Shipping†
MC74ACT241DW	SOIC−20	38 Units / Rail
MC74ACT241DWG	SOIC−20 (Pb−Free)	
MC74ACT241DWR2	SOIC−20	1000 / Tape & Reel
MC74ACT241DWR2G	SOIC−20 (Pb−Free)	
MC74ACT241DTR2	TSSOP−20*	2500 / Tape & Reel
MC74ACT241DTR2G	TSSOP−20*	
MC74ACT241MEL	SOEIAJ−20	2000 / Tape & Reel
MC74ACT241MELG	SOEIAJ−20 (Pb−Free)	

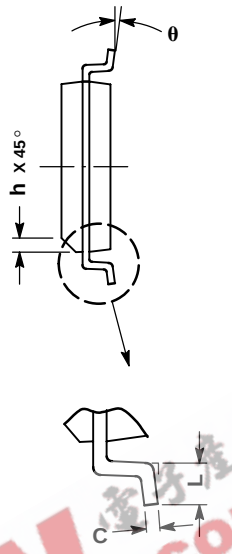
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*These packages are inherently Pb−Free.

PACKAGE DIMENSIONS

SOIC−20W
DW SUFFIX
CASE 751D−05
ISSUE G



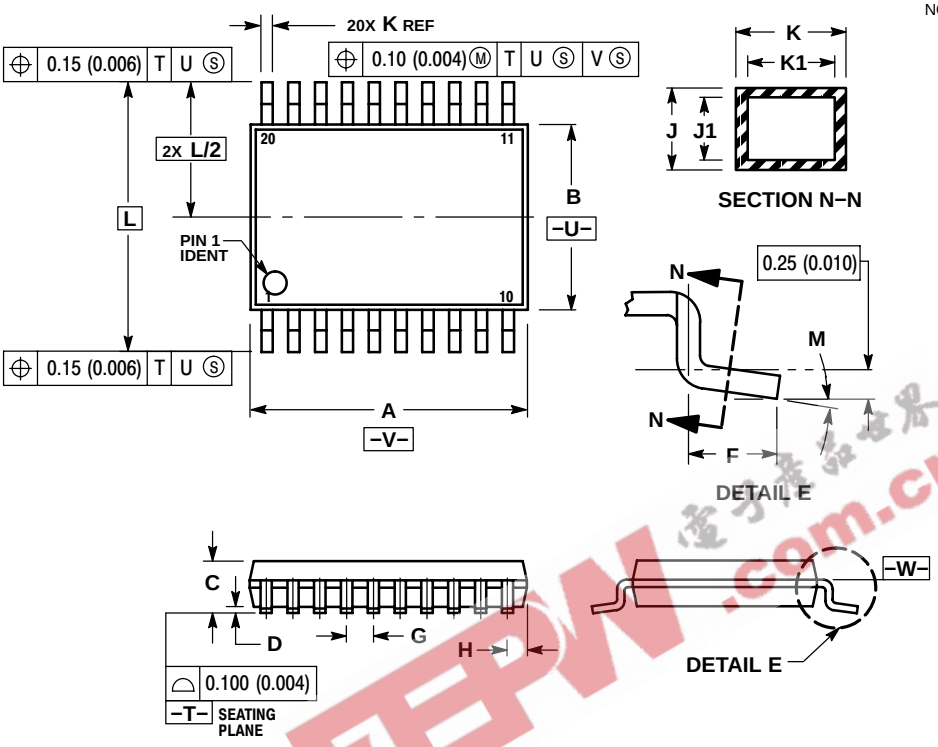


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

PACKAGE DIMENSIONS

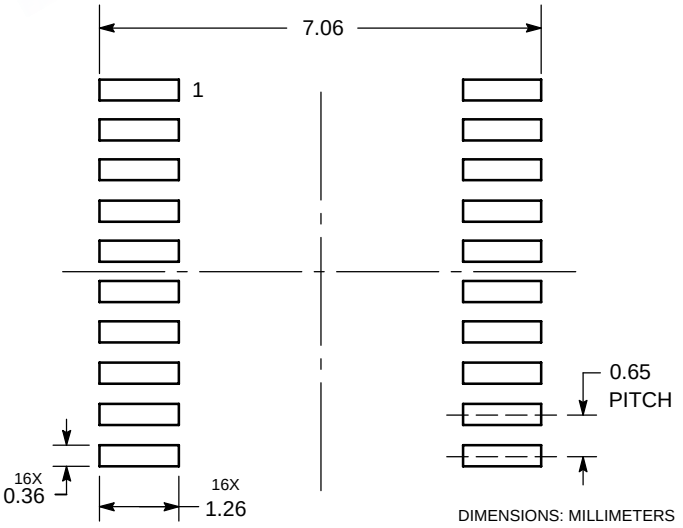
TSSOP−20
DT SUFFIX
CASE 948E−02
ISSUE C



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

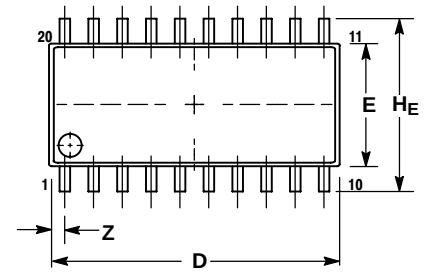


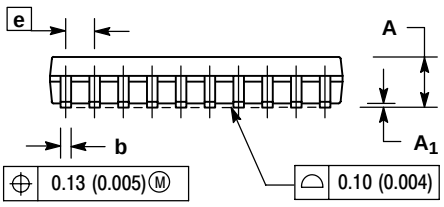
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

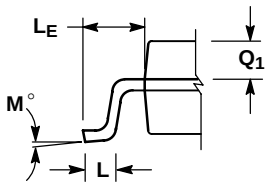
MC74ACT241

PACKAGE DIMENSIONS

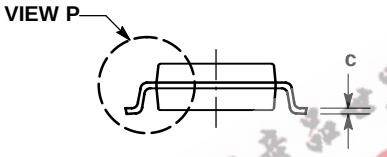
SOEIAJ−20
M SUFFIX
CASE 967−01
ISSUE A







DETAIL P



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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P.O. Box 5163, Denver, Colorado 80217 USA
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Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

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MC74ACT241/D